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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10047119	FILING DATE 01/17/2002	CLASS 250	SUBCLASS	GAU 2878	EXAMINER
<b>**APPLICANTS:</b> Hong Minghui; Ye Kaidong; An Chengwu; Liu Da Ming;					
<b>**CONTINUING DATA VERIFIED:</b>					
<b>** FOREIGN APPLICATIONS VERIFIED:</b> SINGAPORE 200104057-5 07/06/2001					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO 2826-9	
<b>TITLE :</b> Method and apparatus for cutting a multi-layer substrate by dual laser irradiation					

U.S. DEPT. OF COMM. / PAT. & TM-PTO-436L (Rev. 12-94)

<b>NOTICE OF ALLOWANCE MAILED</b>		Assistant Examiner	<b>CLAIMS ALLOWED</b>		
			Total Claims	Print Claim for O.G.	
<b>ISSUE FEE</b>		Primary Examiner	<b>DRAWING</b>		
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.	Print Fig.
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		PREPARED FOR ISSUE	Application Examiner		
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